

TEMIC

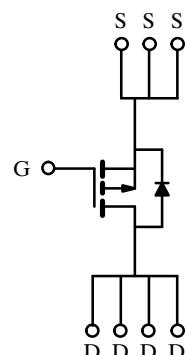
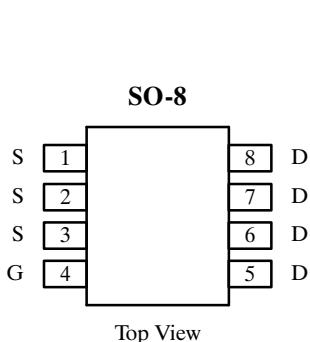
Siliconix

Si9430DY

P-Channel Enhancement-Mode MOSFET

Product Summary

V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-20	0.050 @ $V_{GS} = -10$ V	± 5.8
	0.065 @ $V_{GS} = -6$ V	± 4.9
	0.090 @ $V_{GS} = -4.5$ V	± 4.0



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	± 5.8	A
		± 4.6	
Pulsed Drain Current	I_{DM}	± 15	A
Continuous Source Current (Diode Conduction) ^a	I_S	-2.4	
Maximum Power Dissipation ^a	P_D	2.5	W
		1.6	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C

Thermal Resistance Ratings

Parameter	Symbol	Limit	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	50	°C/W

Notes

a. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Subsequent updates to this data sheet may be obtained via facsimile by calling Siliconix FaxBack, 1-408-970-5600. Please request FaxBack document #1206.

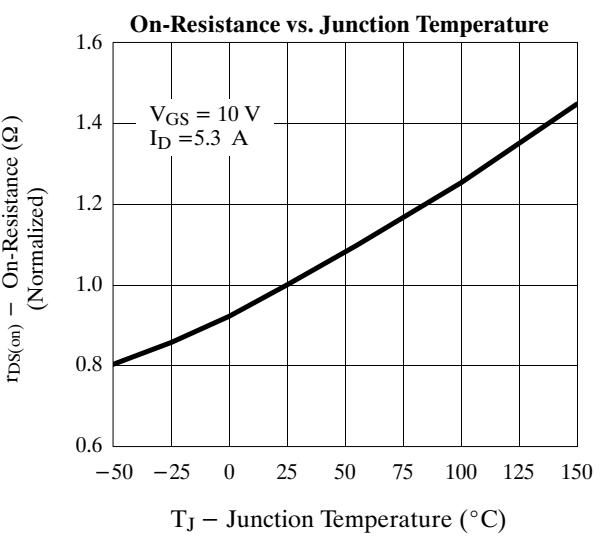
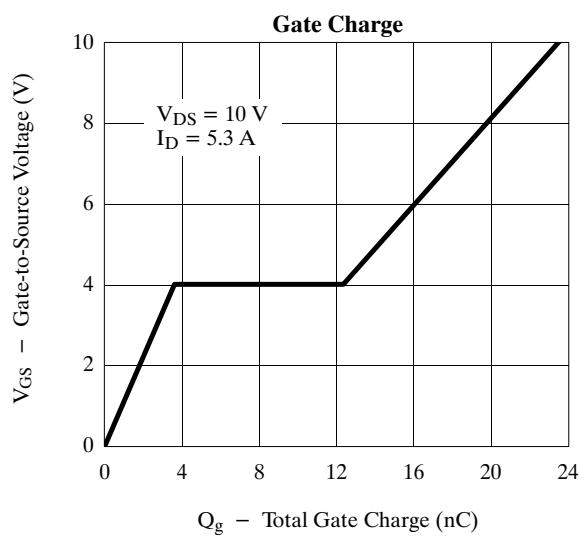
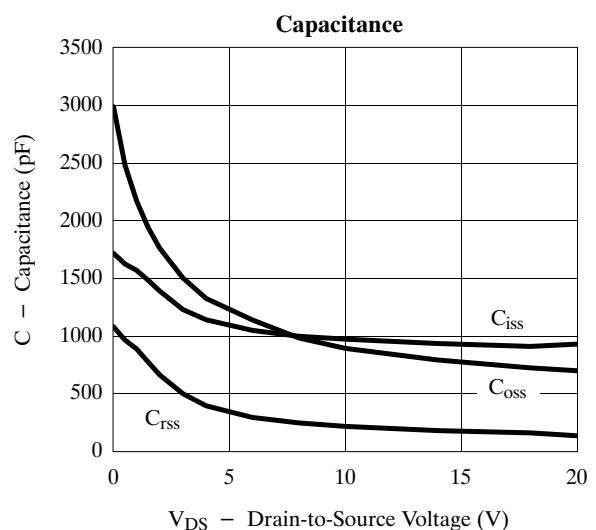
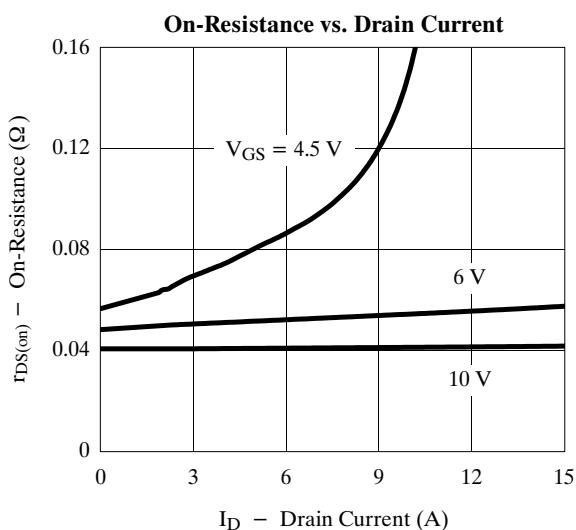
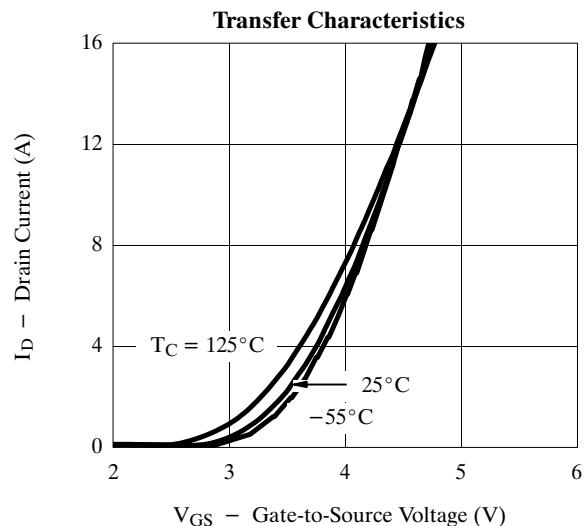
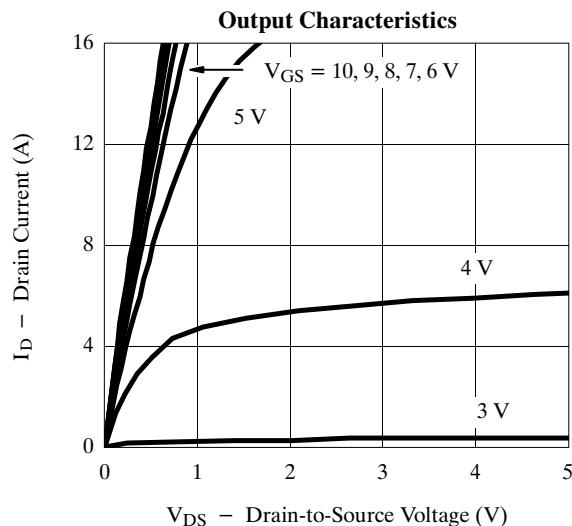
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-1.0			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		± 100		nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$		-1		μA
		$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 70^\circ\text{C}$		-5		
On-State Drain Current ^b	$I_{D(\text{on})}$	$V_{DS} \leq -5 \text{ V}, V_{GS} = -10 \text{ V}$	-15			A
		$V_{DS} \leq -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-3.6			
Drain-Source On-State Resistance ^b	$r_{DS(\text{on})}$	$V_{GS} = -10 \text{ V}, I_D = -5.3 \text{ A}$		0.040	0.050	Ω
		$V_{GS} = -6 \text{ V}, I_D = -3.6 \text{ A}$		0.055	0.065	
		$V_{GS} = -4.5 \text{ V}, I_D = -2.0 \text{ A}$		0.070	0.090	
Forward Transconductance ^b	g_{fs}	$V_{DS} = -15 \text{ V}, I_D = -5.3 \text{ A}$		8.0		S
Diode Forward Voltage ^b	V_{SD}	$I_S = -2.4 \text{ A}, V_{GS} = 0 \text{ V}$		-0.9	-1.2	V
Dynamic^a						
Total Gate Charge	Q_g	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -5.3 \text{ A}$		25	50	nC
Gate-Source Charge	Q_{gs}			5		
Gate-Drain Charge	Q_{gd}			8		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -10 \text{ V}, R_L = 10 \Omega$ $I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6 \Omega$		14	30	ns
Rise Time	t_r			22	60	
Turn-Off Delay Time	$t_{d(\text{off})}$			50	120	
Fall Time	t_f			25	100	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = -2.4 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		85	100	

Notes

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

Typical Characteristics (25°C Unless Otherwise Noted)



Si9430DY**Typical Characteristics (25°C Unless Otherwise Noted)**